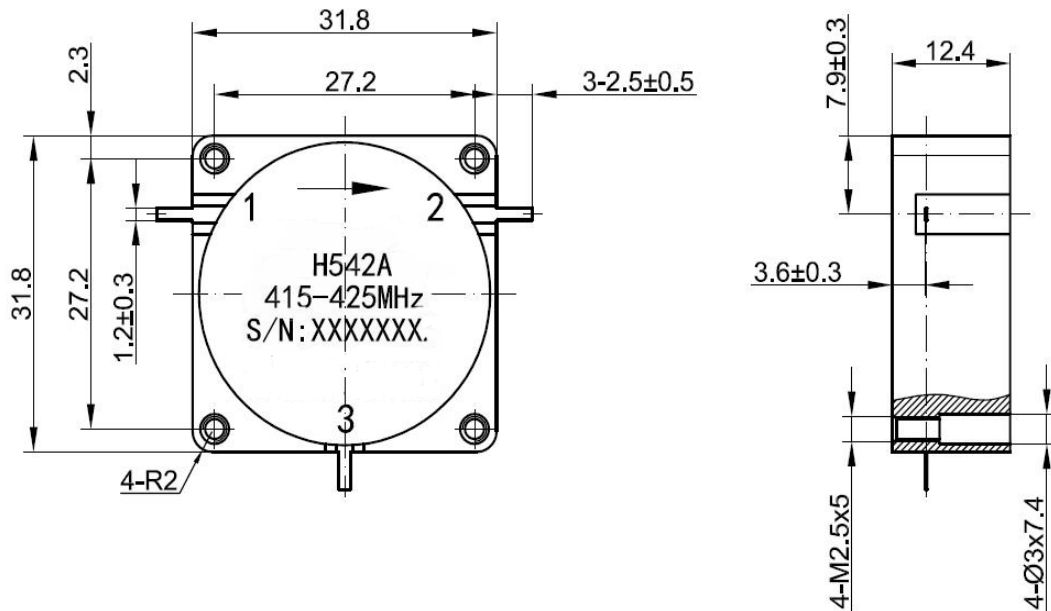


## 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

## 2.Dimensions Unit:mm



## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H542A [415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	100	
H542A [470-510]MHz	0.470	0.510	0.4850	0.040	20	0.15	1.22	100	
H542A [560-680]MHz	0.560	0.680	0.6200	0.080	20	0.15	1.22	100	
H542A [700-960]MHz	0.700	0.960	0.8300	0.260	16	0.5	1.38	300	
H542A [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	400	-75
H542A [1217-1238]MHz	1.217	1.238	1.2275	0.021	23	0.25	1.15	300	
H542A [1565-1586]MHz	1.565	1.586	1.5755	0.021	23	0.25	1.15	300	
H542A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	400	-70
H542A [1800-2175]MHz	1.800	2.175	1.9875	0.375	22	0.3	1.17	300	
H542A [1805-1880]MHz	1.805	1.880	1.838	0.075	25	0.2	1.12	350	-75
H542A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	400	-75